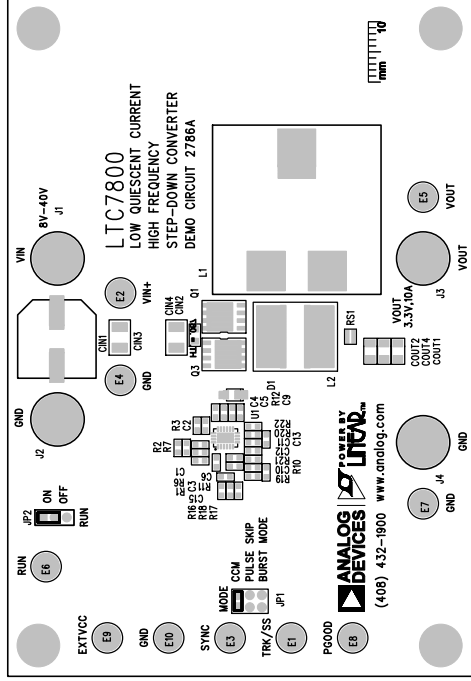
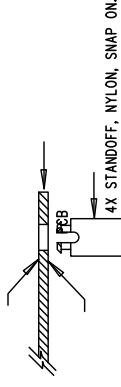




REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	Y.LIU	8-2-18

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



TOP SILKSCREEN

 ANALOG DEVICES  LINEAR <small>TECHNOLOGY</small>		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-9000 WWW.LINEAR.COM	
TITLE: TOP ASSEMBLY DRAWING		FOR OUR CUSTOMER USE ONLY	
LOW QUESCENT CURRENT HIGH FREQUENCY STEP-DOWN CONVERTER		REV. 2	
SIZE IC NO. LTC7800EUDC		DEMO CIRCUIT 2786A	
N/A		SHT 1 OF 2	
SCALE = NONE		FILENAME: DC2786A	
APPROVALS			
PCB DES.	HZ		
APP ENG.	YL		